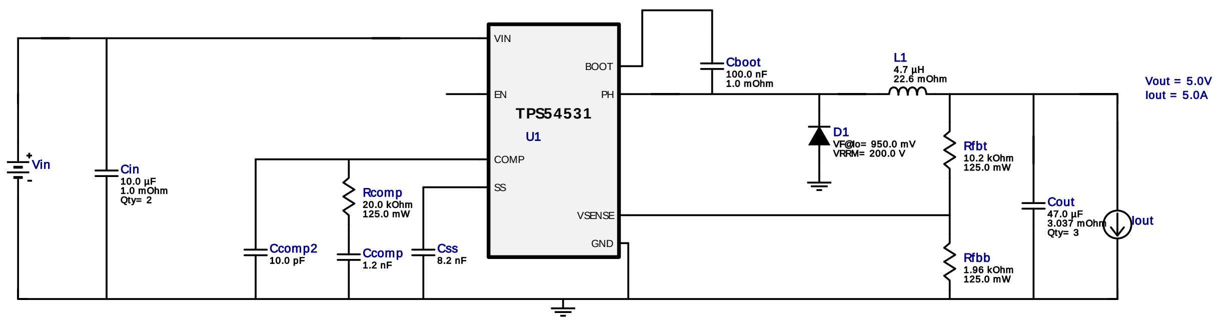
TEXAS INSTRUMENTS

VinMin = 9.0V
VinMax = 22.0V
Vout = 5.0V
Iout = 5.0A

Device = TPS54531DDAR
Topology = Buck
Created = 2019-11-01 13:16:29.055
BOM Cost = $3.30
BOM Count = 15
Total Pd = 5.82W

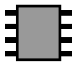
WEBENCH ® Design Report

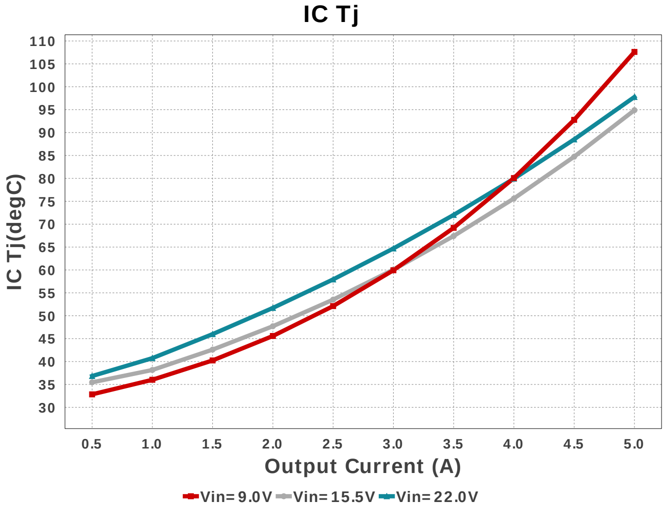
Design : 3 TPS54531DDAR
TPS54531DDAR 9V-22V to 5.00V @ 5A

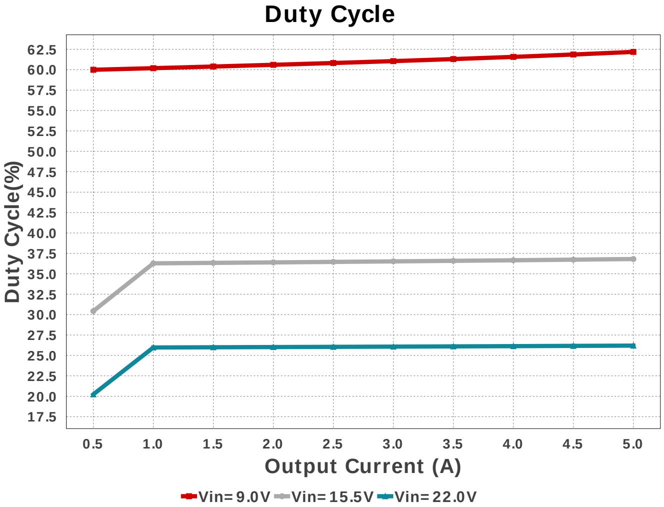


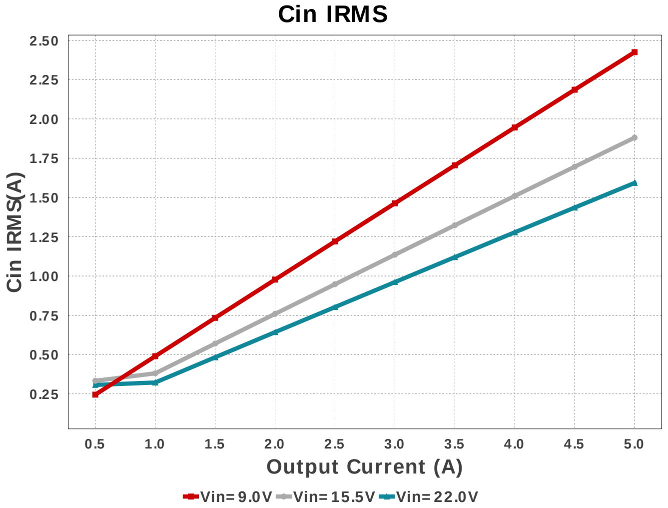
Electrical BOM

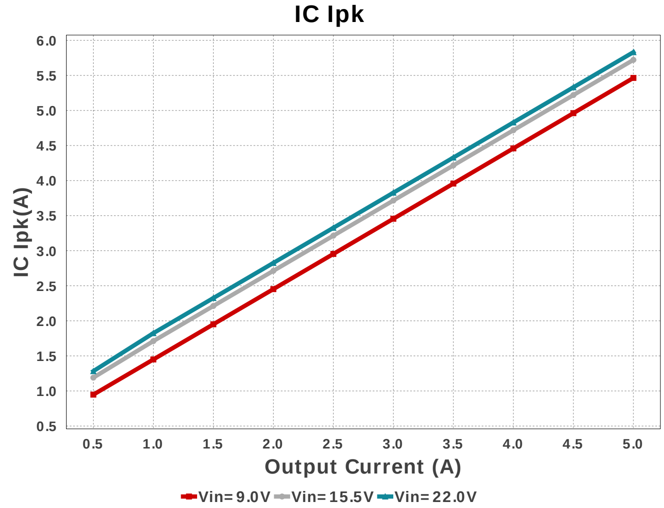
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	Yageo	CC0805KRX7R7BB104 Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm²
Ccomp	Samsung Electro-Mechanics	CL21C122JBFNNNE Series= C0G/NP0	Cap= 1.2 nF VDC= 50.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm²
Ccomp2	Samsung Electro-Mechanics	CL21C100JBANNNC Series= C0G/NP0	Cap= 10.0 pF VDC= 50.0 V IRMS= 0.0 A	1	$0.01	0805 7 mm²
Cin	TDK	C3225X7R1H106M250AC Series= X7R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 5.0 A	2	$0.28	1210 15 mm²
Cout	MuRata	GRM32ER61C476KE15L Series= X5R	Cap= 47.0 uF ESR= 3.037 mOhm VDC= 16.0 V IRMS= 4.59346 A	3	$0.38	1210_280 15 mm²
Css	AVX	12063A822JAT2A Series= C0G/NP0	Cap= 8.2 nF VDC= 25.0 V IRMS= 0.0 A	1	$0.14	1206 11 mm²
D1	SMC Diode Solutions	SBRD10200TR	VF@Io= 950.0 mV VRRM= 200.0 V	1	$0.12	DPAK 102 mm²
L1	Vishay-Dale	IHLP3232DZER4R7M11	L= 4.7 µH 22.6 mOhm	1	$0.66	IHLP-3232DZ 112 mm²
Rcomp	Vishay-Dale	CRCW080520K0FKEA Series= CRCW..e3	Res= 20.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	$0.01	0805 7 mm²
Rfbb	Vishay-Dale	CRCW08051K96FKEA Series= CRCW..e3	Res= 1.96 kOhm Power= 125.0 mW Tolerance= 1.0%	1	$0.01	0805 7 mm²
Rfbt	Vishay-Dale	CRCW080510K2FKEA Series= CRCW..e3	Res= 10.2 kOhm Power= 125.0 mW Tolerance= 1.0%	1	$0.01	0805 7 mm²

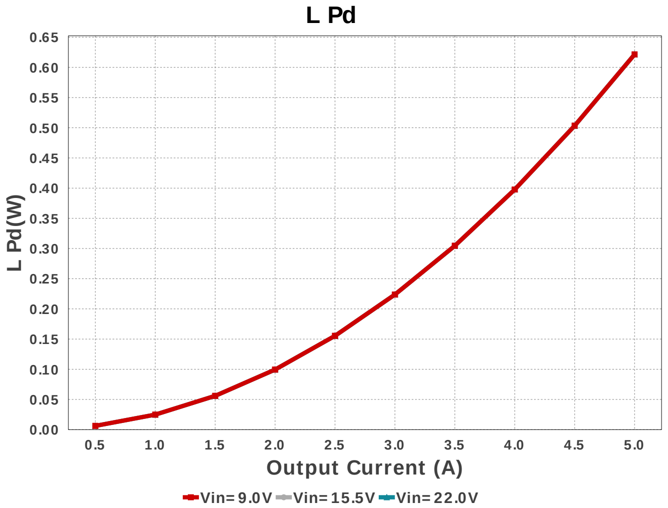
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
U1	Texas Instruments	TPS54531DDAR	Switcher	1	$0.60	 DDA0008E 55 mm²

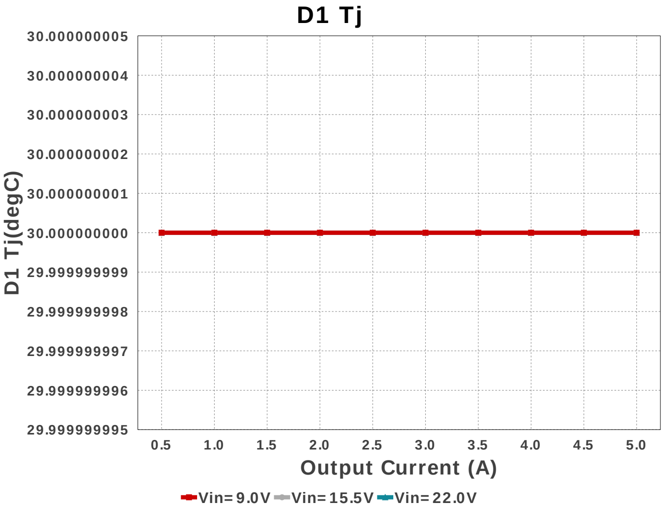




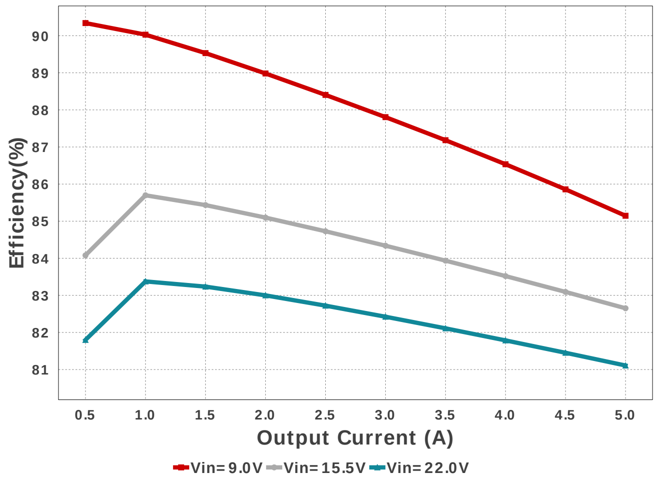




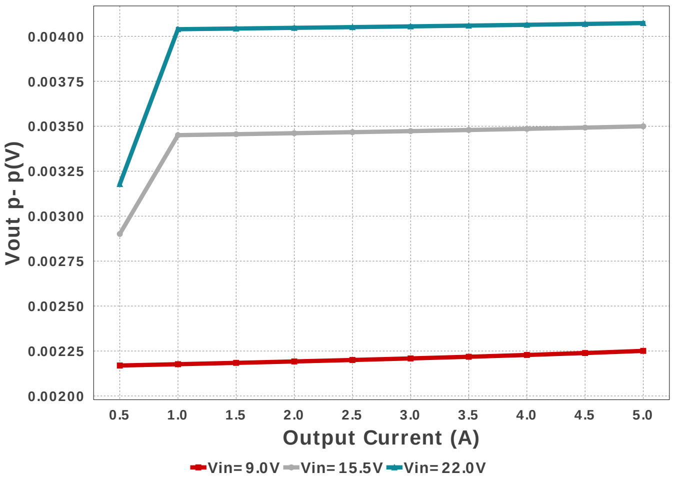




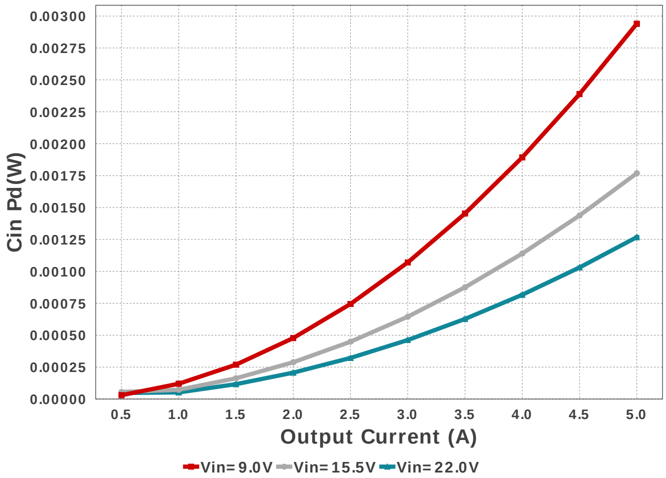
Efficiency



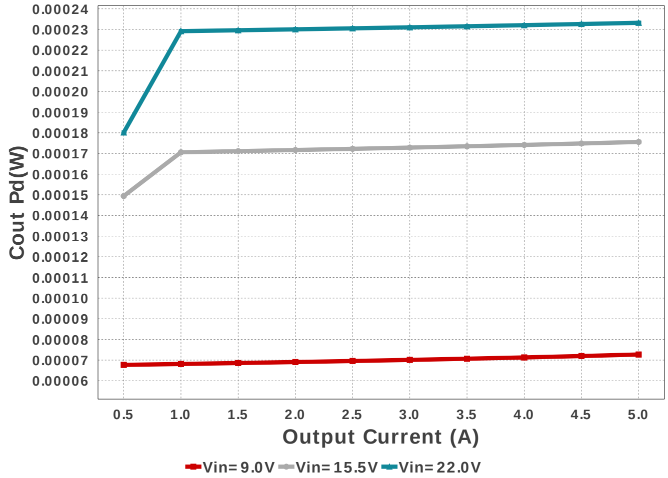
Vout p- p



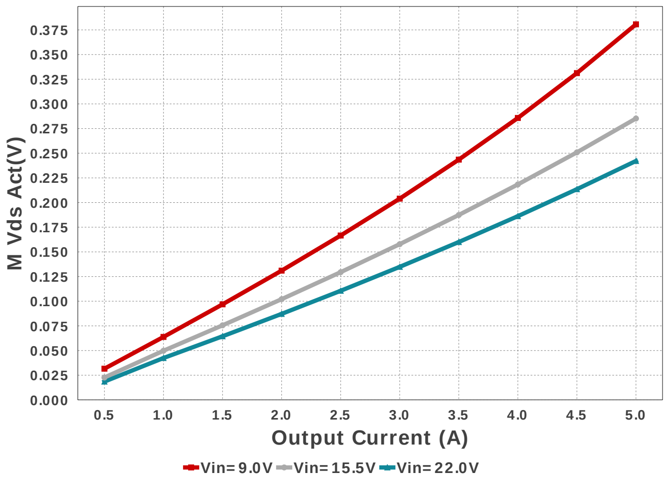
Cin Pd



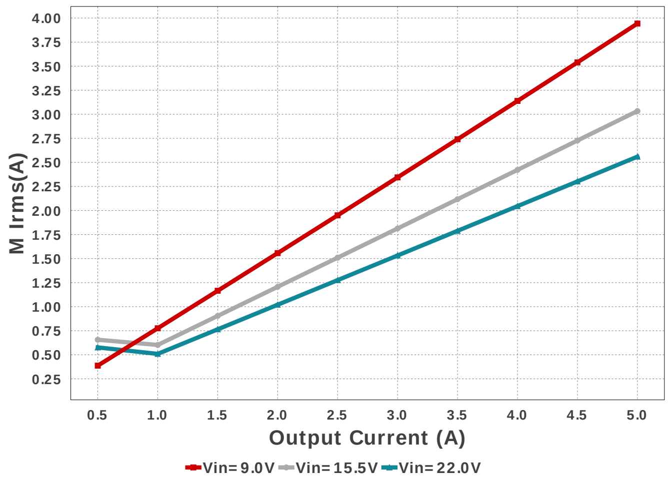
Cout Pd



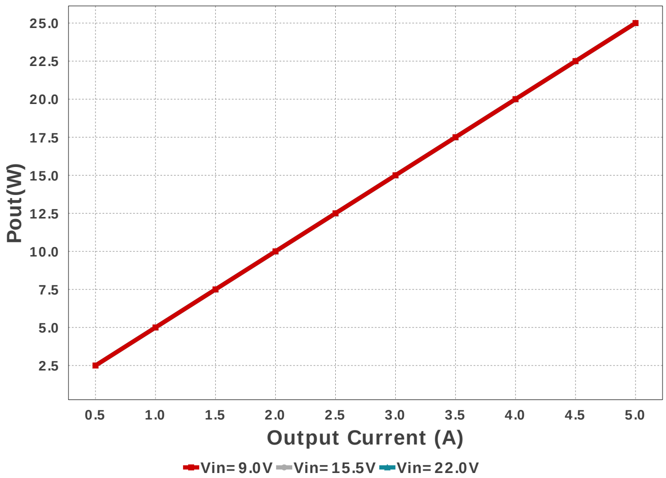
M Vds Act



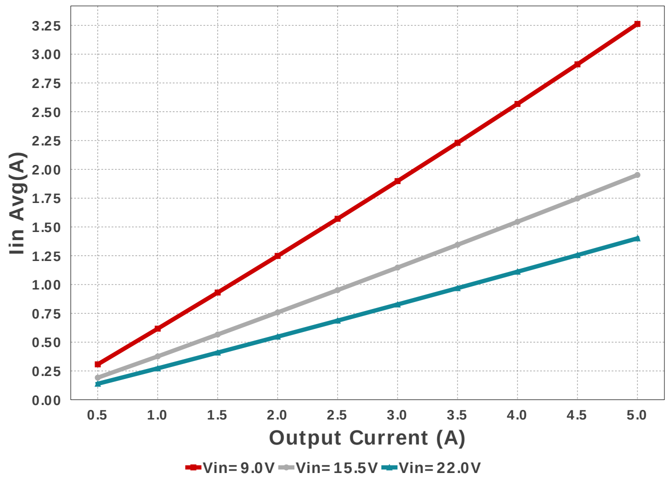
M Irms



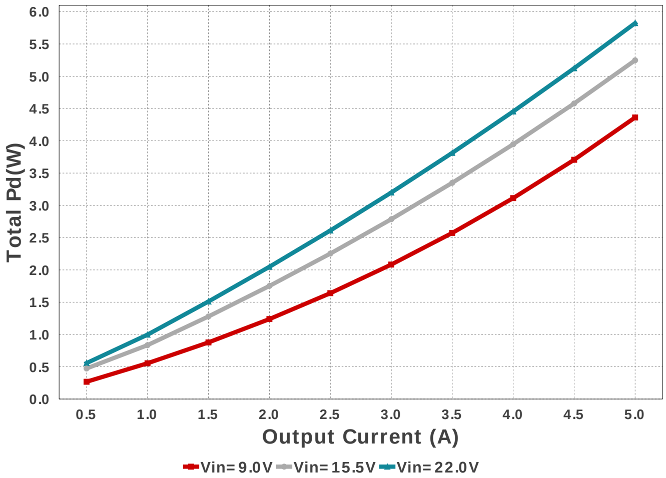
Pout



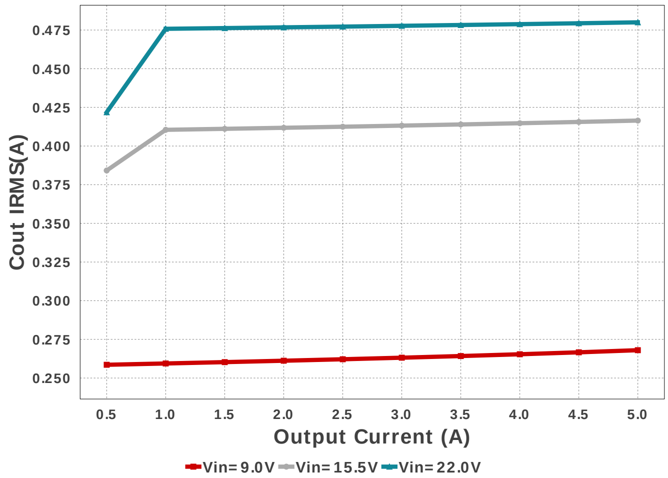
Iin Avg



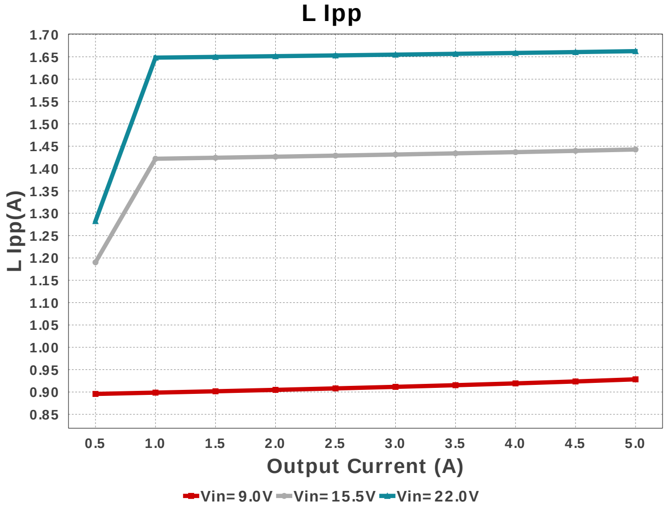
Total Pd



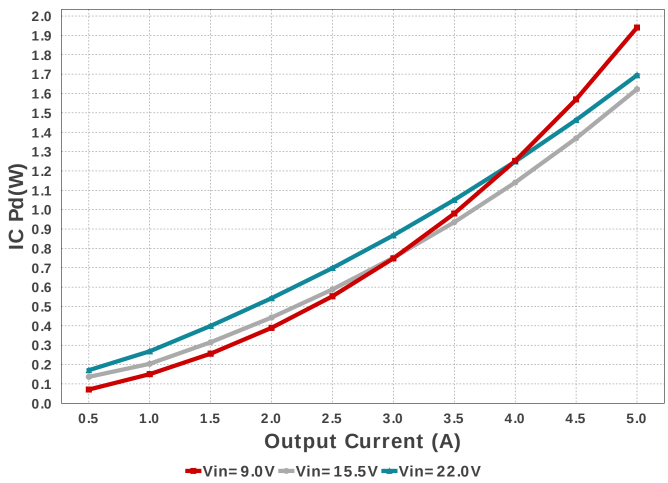
Cout IRMS

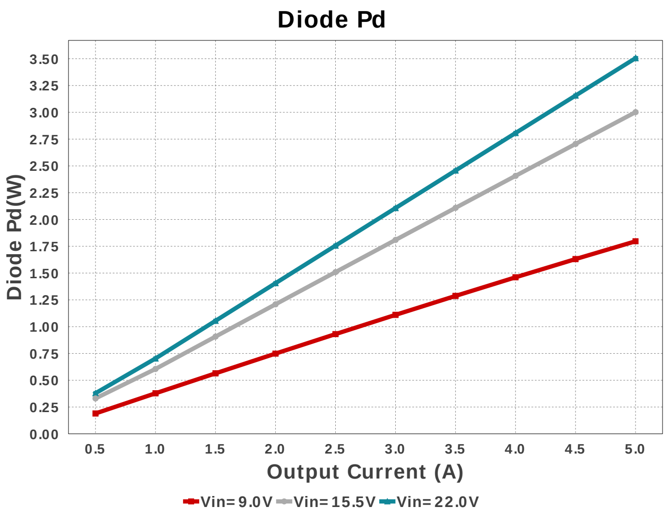


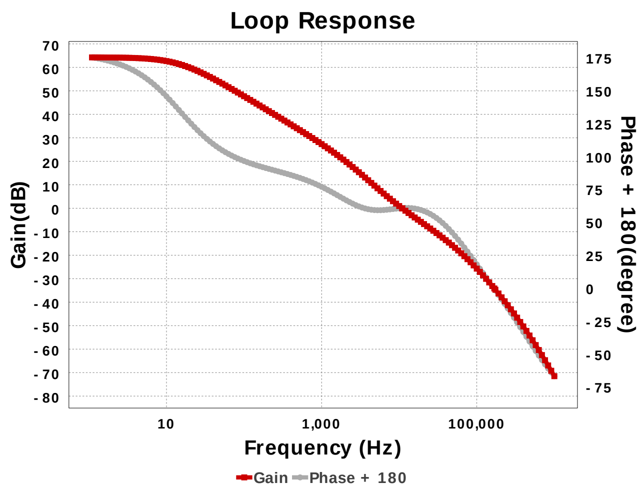
L Ipp



IC Pd







Operating Values

#	Name	Value	Category	Description
1.	BOM Count	15		Total Design BOM count
2.	Total BOM	$3.3		Total BOM Cost
3.	Cin IRMS	1.592 A	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	1.268 mW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	479.984 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	233.23 µW	Capacitor	Output capacitor power dissipation
7.	D1 Tj	30.0 degC	Diode	D1 junction temperature
8.	Diode Pd	3.505 W	Diode	Diode power dissipation
9.	IC Ipk	5.831 A	IC	Peak switch current in IC
10.	IC Pd	1.694 W	IC	IC power dissipation
11.	IC Tj	97.775 degC	IC	IC junction temperature
12.	ICThetaJA	40.0 degC/W	IC	IC junction-to-ambient thermal resistance
13.	Iin Avg	1.401 A	IC	Average input current
14.	L Ipp	1.663 A	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	621.5 mW	Inductor	Inductor power dissipation
16.	M Irms	2.559 A	Mosfet	MOSFET RMS ripple current
17.	M Vds Act	242.159 mV	Mosfet	Voltage drop across the MosFET
18.	Cin Pd	1.268 mW	Power	Input capacitor power dissipation
19.	Cout Pd	233.23 µW	Power	Output capacitor power dissipation
20.	Diode Pd	3.505 W	Power	Diode power dissipation
21.	IC Pd	1.694 W	Power	IC power dissipation
22.	L Pd	621.5 mW	Power	Inductor power dissipation
23.	Total Pd	5.823 W	Power	Total Power Dissipation
24.	Cross Freq	10.908 kHz	System Information	Bode plot crossover frequency
25.	Duty Cycle	26.202 %	System Information	Duty cycle
26.	Efficiency	81.109 %	System Information	Steady state efficiency
27.	FootPrint	394.0 mm^2	System Information	Total Foot Print Area of BOM components
28.	Frequency	570.0 kHz	System Information	Switching frequency
29.	Gain Marg	-34.151 dB	System Information	Bode Plot Gain Margin
30.	Iout	5.0 A	System Information	Iout operating point
31.	Low Freq Gain	64.258 dB	System Information	Gain at 1Hz
32.	Mode	CCM	System Information	Conduction Mode
33.	Phase Marg	61.384 deg	System Information	Bode Plot Phase Margin
34.	Pout	25.0 W	System Information	Total output power
35.	Vin	22.0 V	System Information	Vin operating point
36.	Vout	5.0 V	System Information	Operational Output Voltage
37.	Vout Actual	4.963 V	System Information	Vout Actual calculated based on selected voltage divider resistors

#	Name	Value	Category	Description
38.	Vout Tolerance	5.254 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
39.	Vout p-p	4.073 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	5.0	Maximum Output Current
VinMax	22.0	Maximum input voltage
VinMin	9.0	Minimum input voltage
VinTyp	12.0	Typical input voltage
Vout	5.0	Output Voltage
base_pn	TPS54531	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

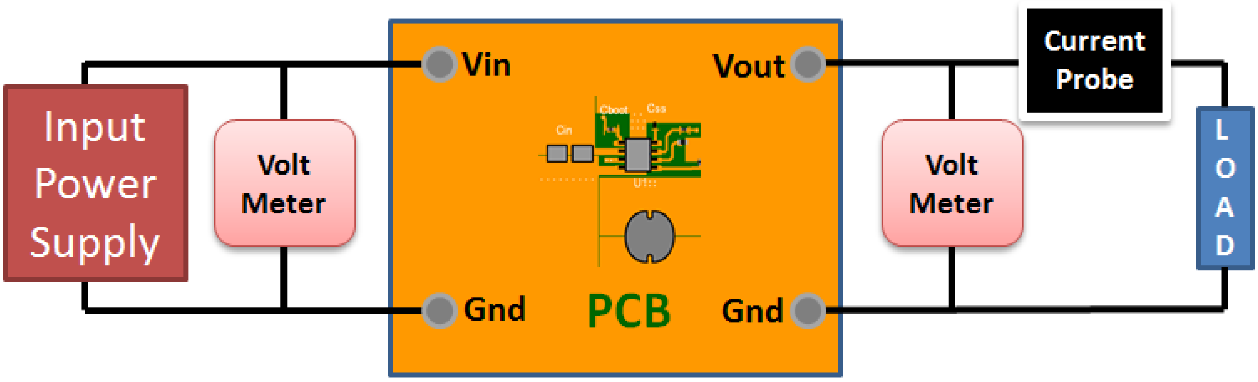
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 9.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : 2128C7AEB785B442[v1]

2. **TPS54531** Product Folder : http://www.ti.com/product/TPS54531 : contains the data sheet and other resources.